



EV318282163

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and
Bonding Frames

#15gw10/01/03

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

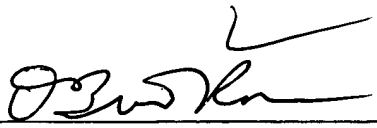
References -See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

Dated: 9-4-03

By: 
D. Brent Kenady
Reg. No. 40,045

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